



### PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

## **Features**

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (MMST4401)
- Ultra-Small Surface Mount Package
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)

SOT-323

### **Mechanical Data**

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Weight: 0.006 grams (approximate)



Top view





Device symbol

Pinout - top view

## Ordering Information (Note 3)

Device	Packaging	Shipping
MMST4403-7-F	SOT-323	3000/Tape & Reel

Notes: 1. No purposefully added lead.

2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

3. For packaging details, go to our website at http://www.diodes.com

# **Marking Information**



K3T = Product Type Marking Code YM = Date Code Marking Y = Year ex: N = 2002M = Month ex: 9 = September

Date Code Key

Year	2010		2011	2012		2013	2014		2015	2016		2017
Code	Х		Y	Z		А	В		С	D		E
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Νον	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-40	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-40	V
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	V
Collector Current – Continuous (Note 4)	Ι <sub>C</sub>	-600	mA
Power Dissipation (Note 4)	Pd	200	mW
Thermal Resistance, Junction to Ambient (Note 4)	R <sub>θJA</sub>	625	K/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch;

# **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)						
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	-40		V	$I_{C} = -100 \mu A, I_{E} = 0$	
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	-40		V	I <sub>C</sub> = -1.0mA, I <sub>B</sub> = 0	
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	-5.0		V	$I_{E} = -100 \mu A, I_{C} = 0$	
Collector Cutoff Current	I <sub>CEX</sub>		-100	nA	$V_{CE} = -35V, V_{EB(OFF)} = -0.4V$	
Base Cutoff Current	I <sub>BL</sub>	_	-100	nA	$V_{CE} = -35V, V_{EB(OFF)} = -0.4V$	
ON CHARACTERISTICS (Note 5)	•		•		•	
DC Current Gain	h <sub>FE</sub>	30 60 100 100 20	  300		$ \begin{array}{l} I_{C} = -100 \mu A, \ V_{CE} = -1.0V \\ I_{C} = -1.0mA, \ V_{CE} = -1.0V \\ I_{C} = -10mA, \ V_{CE} = -1.0V \\ I_{C} = -150mA, \ V_{CE} = -2.0V \\ I_{C} = -500mA, \ V_{CE} = -2.0V \end{array} $	
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>		-0.40 -0.75	V	$I_{C} = -150$ mA, $I_{B} = -15$ mA $I_{C} = -500$ mA, $I_{B} = -50$ mA	
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	-0.75	-0.95 -1.30	V	$I_{C} = -150mA$ , $I_{B} = -15mA$ $I_{C} = -500mA$ , $I_{B} = -50mA$	
SMALL SIGNAL CHARACTERISTICS	•		•		•	
Output Capacitance	C <sub>ob</sub>	—	8.5	pF	V <sub>CB</sub> = -10V, f = 1.0MHz, I <sub>E</sub> = 0	
Input Capacitance	C <sub>eb</sub>		30	pF	V <sub>EB</sub> = -0.5V, f = 1.0MHz, I <sub>C</sub> = 0	
Input Impedance	h <sub>ie</sub>	1.5	15	kΩ		
Voltage Feedback Ratio	h <sub>re</sub>	0.1	8.0	x 10 <sup>-4</sup>	V <sub>CE</sub> = -10V, I <sub>C</sub> = -1.0mA,	
Small Signal Current Gain	h <sub>fe</sub>	60	500	—	f = 1.0MHz	
Output Admittance	h <sub>oe</sub>	1.0	100	μS		
Current Gain-Bandwith Product	f <sub>T</sub>	200		MHz	$V_{CE} = -10V, I_C = -20mA,$ f = 100MHz	
SWITCHING CHARACTERISTICS	•		•		•	
Delay Time	t <sub>d</sub>	_	15	ns	V <sub>CE</sub> = -30V, I <sub>C</sub> = -150mA,	
Rise Time	tr	_	20	ns	$V_{BE(OFF)} = -2.0V, I_{B1} = -15mA$	
Storage Time	ts	_	225	ns	V <sub>CE</sub> = -30V, I <sub>C</sub> = -150mA,	
Fall Time	tr		30	ns	$I_{B1} = I_{B2} = -15 \text{mA}$	

Notes: 5. Short duration pulse test used to minimize self-heating effect



# **MMST4403**





MMST4403 Datasheet number: DS30083 Rev. 8 - 2





# Package Outline Dimensions



SOT-323							
Dim	Min	Max	Тур				
Α	0.25	0.40	0.30				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D	-	-	0.65				
G	1.20	1.40	1.30				
н	1.80	2.20	2.15				
J	0.0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
М	0.10 0.18		0.11				
N	-	-	-				
α	0°	8°	-				
All Dimensions in mm							



## Suggested Pad Layout



Dimensions	SOT-323
Z	2.8
X	0.7
Y	0.9
С	1.9
E	1.0

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